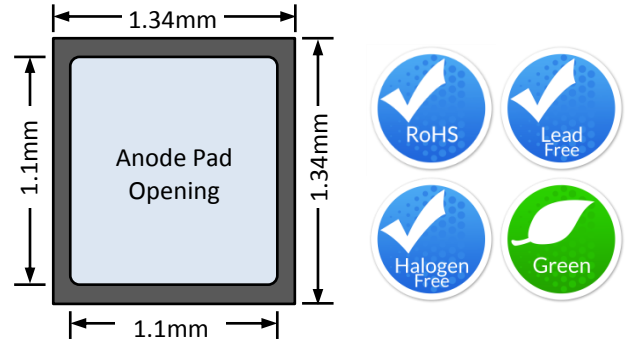


## Description

United Silicon Carbide, Inc. offers the xR series of high performance SiC Schottky diodes. With zero reverse recovery charge and 175°C maximum junction temperature, USCi's diodes are ideally suited for high frequency and high efficiency power systems with minimum cooling requirements.



Part Number	Anode Metal	Cathode Metal	Packaging
UJD06508Z	Al 5µm	Ti/Ni/Au 0.07/0.1/0.1µm	Die on Tape

## Features

- ◆ Positive temperature coefficient for safe operation and ease of paralleling
- ◆ 175°C maximum operating junction temperature
- ◆ Extremely fast switching not dependent on temperature
- ◆ Essentially no reverse or forward recovery
- ◆ RoHS compliant

## Typical Applications

- ◆ Power converters
- ◆ Industrial motor drives
- ◆ Switching-mode power supplies
- ◆ Power factor correction modules

## Maximum Ratings

Parameter	Symbol	Test Conditions	Value	Units
DC blocking voltage	$V_R$		650	V
Repetitive peak reverse voltage, $T_j=25^\circ\text{C}$	$V_{RRM}$		650	V
Surge peak reverse voltage	$V_{RSM}$		650	V
Maximum DC forward current <sup>(1)</sup>	$I_F$	$T_C = 152^\circ\text{C}$	8	A
Non-repetitive forward surge current <sup>(1)</sup> sine halfwave	$I_{FSM}$	$T_C = 25^\circ\text{C}, t_p = 10\text{ms}$	60	A
		$T_C = 110^\circ\text{C}, t_p = 10\text{ms}$	48	
Repetitive forward surge current <sup>(1)</sup> sine halfwave, $D=0.1$	$I_{FRM}$	$T_C = 25^\circ\text{C}, t_p = 10\text{ms}$	34.5	A
		$T_C = 110^\circ\text{C}, t_p = 10\text{ms}$	21.5	
Non-repetitive peak forward current <sup>(1)</sup>	$I_{F,max}$	$T_C = 25^\circ\text{C}, t_p = 10\mu\text{s}$	385	A
		$T_C = 110^\circ\text{C}, t_p = 10\mu\text{s}$	347	
Non-repetitive avalanche energy <sup>(1)</sup>	$E_{AS}$	$T_j = 25^\circ\text{C}, L = 5\text{mH},$ $I_{pk}=4.9\text{A}, V_{DD}=100\text{V}$	67	mJ
Maximum junction temperature	$T_{j,max}$		175	°C
Operating and storage temperature	$T_j, T_{STG}$		-55 to 175	°C

(1) Assumes a maximum junction-to-case thermal resistance of 1.3°C/W.

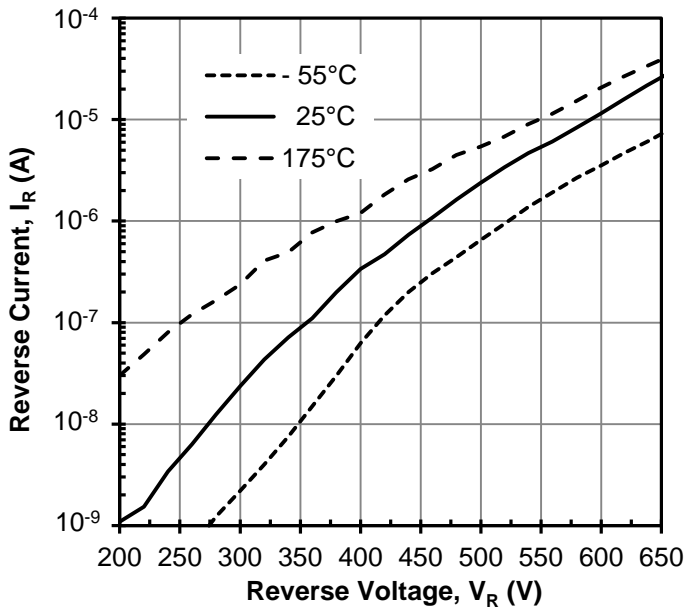
**Electrical Characteristics**

$T_J = +25^\circ\text{C}$  unless otherwise specified

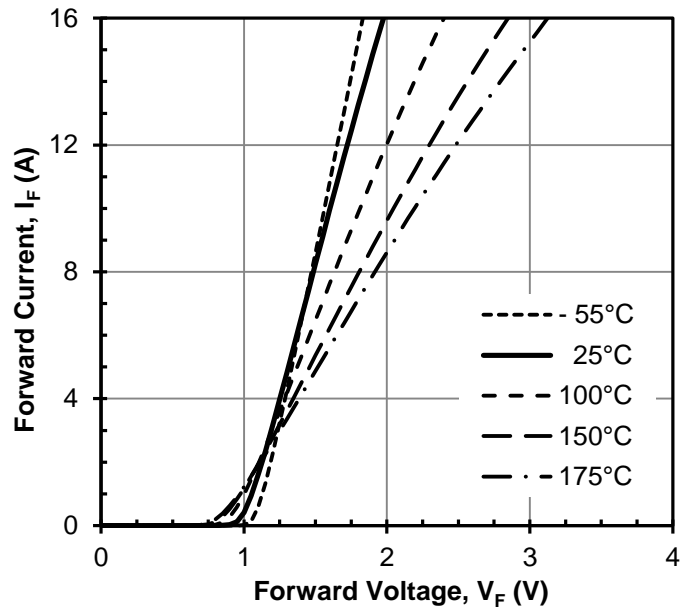
Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Forward voltage	$V_F$	$I_F = 8\text{A}, T_J = 25^\circ\text{C}$	-	1.5	1.7	V
		$I_F = 8\text{A}, T_J = 150^\circ\text{C}$	-	1.8	2.1	
		$I_F = 8\text{A}, T_J = 175^\circ\text{C}$	-	1.95	2.25	
Reverse current	$I_R$	$V_R = 650\text{V}, T_J = 25^\circ\text{C}$	-	20	230	$\mu\text{A}$
		$V_R = 650\text{V}, T_J = 175^\circ\text{C}$	-	40	700	
Total capacitive charge <sup>(2)</sup>	$Q_C$	$V_R = 400\text{V}$		18		nC
Total capacitance	C	$V_R = 1\text{V}, f = 1\text{MHz}$		260		pF
		$V_R = 300\text{V}, f = 1\text{MHz}$		29		
		$V_R = 600\text{V}, f = 1\text{MHz}$		23		
Capacitance stored energy	$E_C$	$V_R = 400\text{V}$		2.6		$\mu\text{J}$

(2) See Figure 4,  $Q_C$  is independent on  $T_J$ ,  $di_F/dt$ , and  $I_F$  as shown in the application note USCi\_AN0011.

**Typical Performance**



**Figure 1 Typical reverse characteristics**



**Figure 2 Typical forward characteristics**

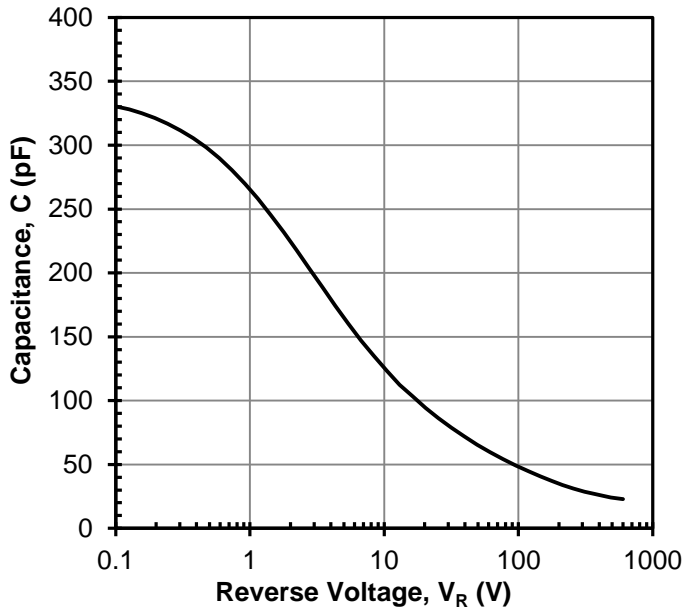


Figure 3 Capacitance vs. reverse voltage

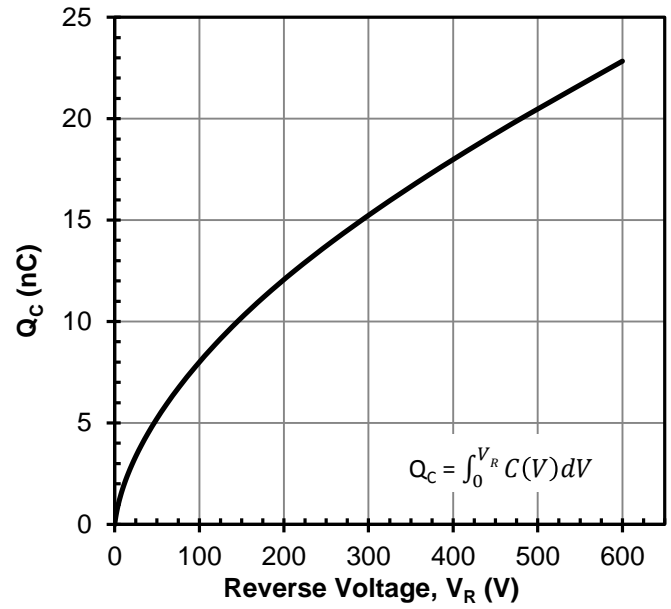


Figure 4 Typical capacitive charge vs. reverse voltage

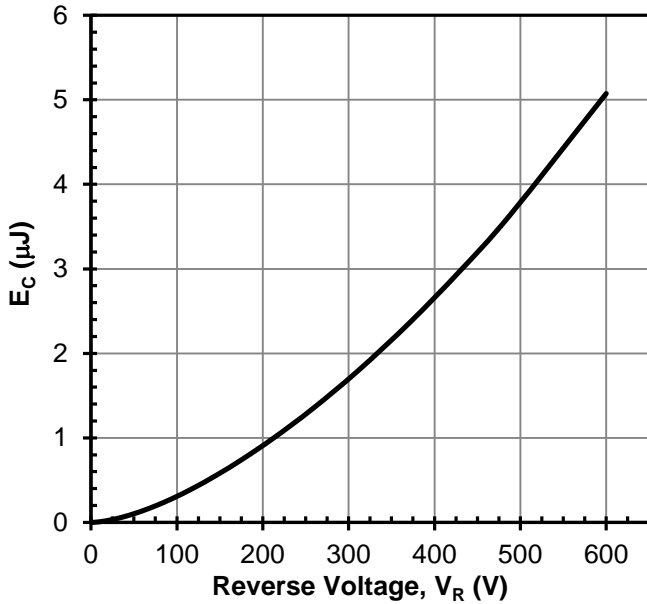


Figure 5 Typical capacitance stored energy vs. reverse voltage

## Mechanical Characteristics

Parameter	Typical Value	Units
Die Dimensions (L x W)	1.34 x 1.34	mm
Top Anode Pad Opening (L x W)	1.1 x 1.1	mm
Wafer Size	100	mm
Anode Metallization (Al)	5	μm
Cathode Metallization (Ti/Ni/Au)	0.07/0.1/0.1	μm
Frontside Passivation BCB	5.5	μm
Die Thickness	100	μm

## Disclaimer

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